



**DDR4 DIMM**

TE Internal #: 2199154-1

TE Internal Description: DDR4 DIMM 288 Pin TH type

DDR4 DIMM SOCKETS

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Connectors > Socket Connectors > Memory Sockets > DIMM Sockets > DDR4 DIMM SOCKETS



DRAM Type: **Double Data Rate (DDR) 4**

Connector System: **Board-to-Board**

Number of Positions: **288**

Termination Method to PCB: **Through Hole - Solder**

Module Orientation: **Vertical**

[All DDR4 DIMM SOCKETS \(25\)](#)

**Features**

**Product Type Features**

Connector & Contact Terminates To	Printed Circuit Board
DRAM Type	Double Data Rate (DDR) 4
Connector System	Board-to-Board

**Configuration Features**

Number of Keys	1
Number of Bays	2
Number of Rows	2
Number of Positions	288
Module Orientation	Vertical

**Electrical Characteristics**

DRAM Voltage	1.2 V
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**Body Features**

Retention Post Location	None
Latch Color	Black
Latch Material	High Temperature Thermoplastic
PCB Retention Feature Material	Stainless Steel

Ejector Material Color	Natural
Module Key Type	Offset Right
Ejector Location	Both Ends
Ejector Material	High Temperature Thermoplastic
Ejector Type	Standard

### Contact Features

Contact Underplating Material	Nickel
Socket Style	DIMM
Contact Mating Area Plating Material Thickness	.38 $\mu\text{m}$ [15 $\mu\text{in}$ ]
PCB Contact Termination Area Plating Material Thickness	3 $\mu\text{m}$ [118.1 $\mu\text{in}$ ]
Contact Mating Area Plating Material	Gold (Au)
Memory Socket Type	Memory Card
Contact Base Material	Copper Alloy
PCB Contact Termination Area Plating Material	Tin
Contact Current Rating (Max)	.75 A

### Termination Features

Insertion Style	Direct Insert
Termination Post & Tail Length	2.67 mm[.105 in]
Termination Method to PCB	Through Hole - Solder

### Mechanical Attachment

Connector Mounting Type	Board Mount
PCB Mount Retention	With
Mount Angle	Vertical
PCB Mount Retention Type	Boardlock
Mating Alignment Type	Offset Right
Mating Alignment	With

### Housing Features

Housing Color	Black
Housing Material	High Temperature Nylon
Centerline (Pitch)	.85 mm[.033 in]

### Dimensions

Center Retention Hole Diameter	1.2 mm[.047 in]
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Profile Height from PCB	20 mm[.787 in]
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Row-to-Row Spacing	2.2 mm[.08 in]
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### Usage Conditions

Operating Temperature Range	-55 – 105 °C[-67 – 221 °F]
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### Operation/Application

Circuit Application	Signal
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### Industry Standards

UL Flammability Rating	UL 94V-0
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### Packaging Features

Packaging Quantity	80
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Packaging Method	Box & Tray, Tray
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## Product Compliance

[For compliance documentation, visit the product page on TE.com>](#)

EU RoHS Directive 2011/65/EU	Compliant
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EU ELV Directive 2000/53/EC	Not Yet Reviewed
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China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
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EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JAN 2025 (247) Candidate List Declared Against: JUL 2019 (201) Does not contain REACH SVHC
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Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
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Solder Process Capability	Wave solder capable to 260°C
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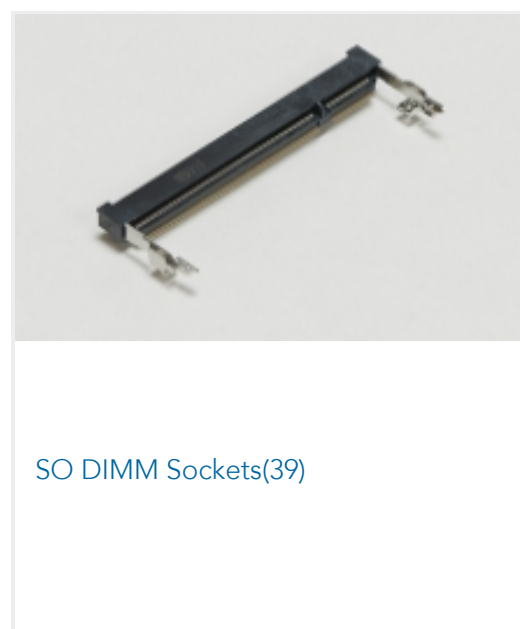
#### Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

## Compatible Parts



## Also in the Series | DDR4 DIMM



## Customers Also Bought



## Documents

[Product Drawings](#)

[DDR4 DIMM 288 Pin TH type](#)

English

[CAD Files](#)



Customer View Model

[ENG\\_CVM\\_CVM\\_2199154-1\\_C5.3d\\_igs.zip](#)

English

Customer View Model

[ENG\\_CVM\\_CVM\\_2199154-1\\_C5.3d\\_stp.zip](#)

English

**3D PDF**

3D

Customer View Model

[ENG\\_CVM\\_CVM\\_2199154-1\\_C5.2d\\_dxf.zip](#)

English

By downloading the CAD file I accept and agree to the [Terms and Conditions](#) of use.

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**Datasheets & Catalog Pages**

[DDR4 DIMM Socket Flyer \(English\)](#)

English

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**Product Specifications**

[Product Specification](#)

English

[Product Specification](#)

English